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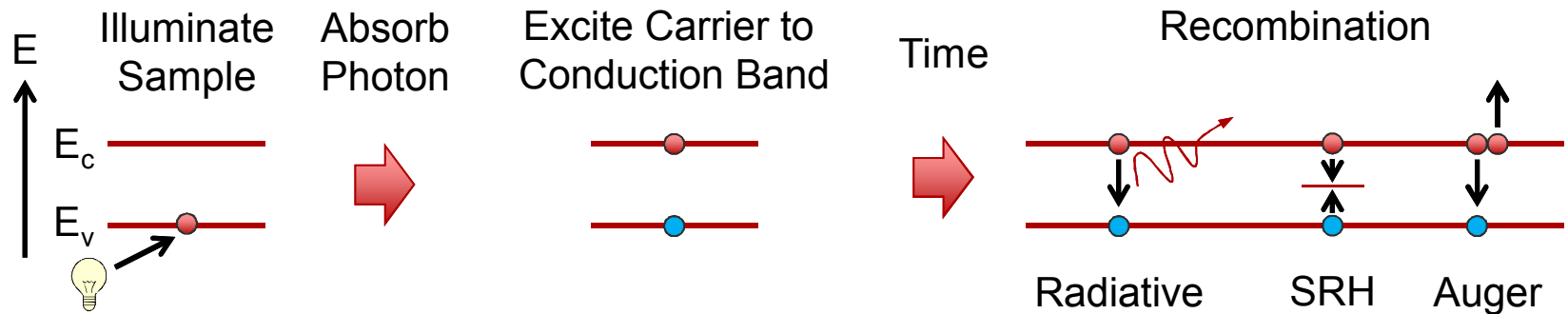


Rapid PL Imaging For Defect Identification in Semiconductor Sensors

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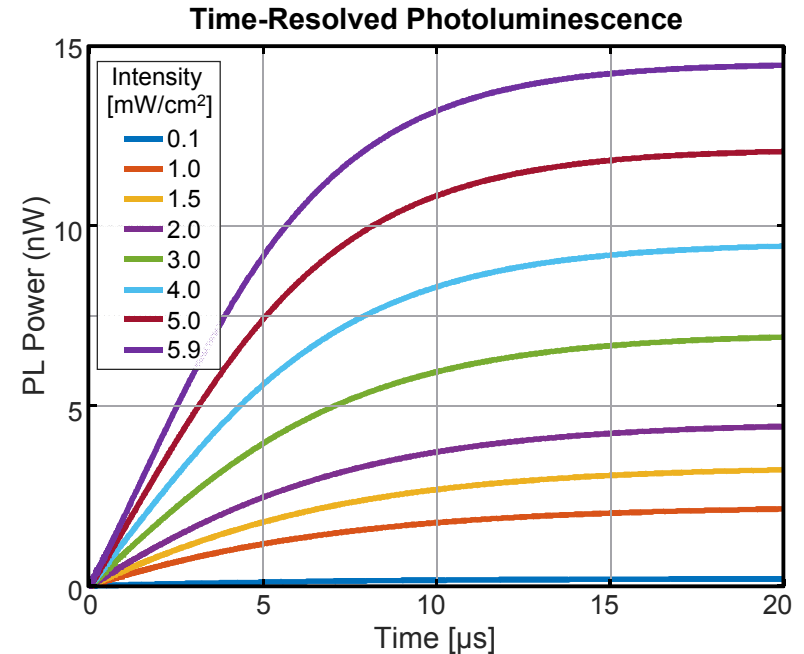
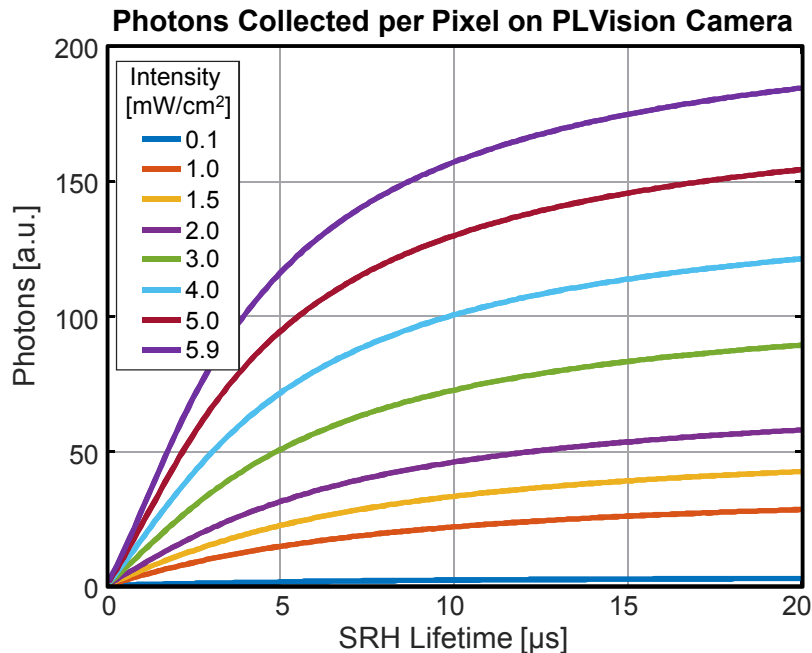
- **Goal: identify defects early in production to increase yield and quality of large IR FPAs**
- Photoluminescence (PL)
 - Lifetime and intensity depend on carrier recombination time
 - Provides direct indication of material quality
 - Doesn't require finished device: works equally well at any stage from unpatterned wafers to finished devices
- Previously showed lifetime mapping could identify defects in MCT FPAs
 - Only need *variation* in lifetime to identify defects
- *PLVision*: image mid-IR PL intensity with camera
 - Correlates well with lifetime variation and defects in arrays
 - Fast: collect from a large area at once, potentially room-temperature sample
 - Much simpler setup
- Focus on short-wave IR MCT arrays

Photoluminescence



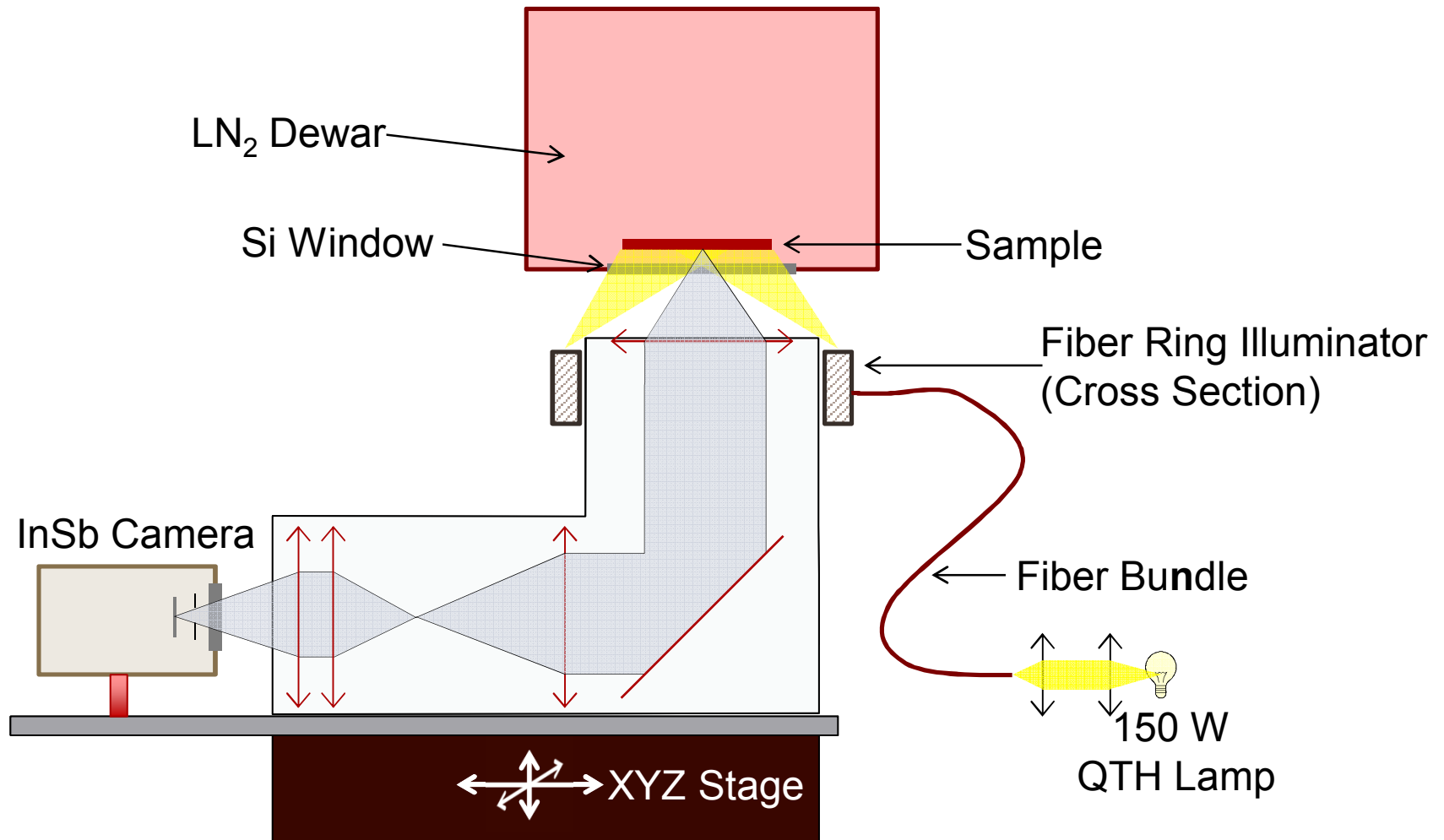
- Three primary decay mechanisms: Radiative, SRH, and Auger
- Radiative recombination: photoluminescence
- Relative rate of decay mechanisms control intensity
- More defects \rightarrow more trap states \rightarrow increase SRH rate \rightarrow reduced PL & reduced performance

Lifetime → Observed PL



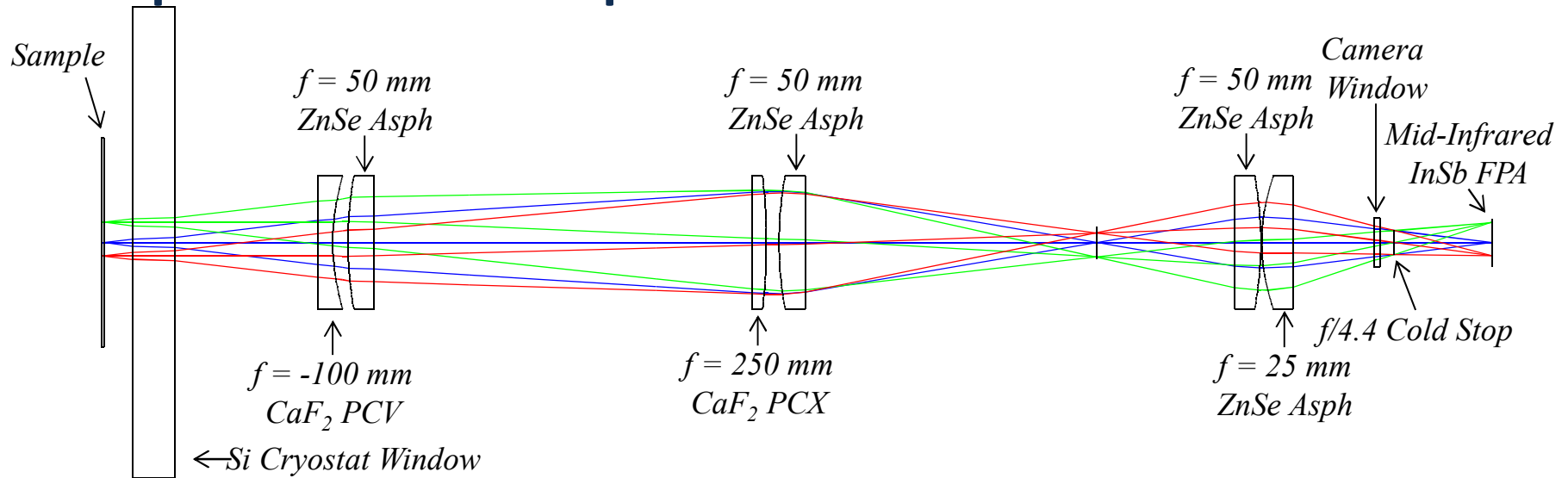
- Carrier recombination simulation with CW excitation starting at $T = 0$
- SRH lifetime for FPA #1 is in this range
- PL Intensity vs. lifetime not linear, but clearly can identify differences in lifetime simply by imaging PL intensity
- Input intensity important:
 - High intensity: PL contrast only for short SRH lifetimes
 - Low intensity: No signal

Experiment: Overview

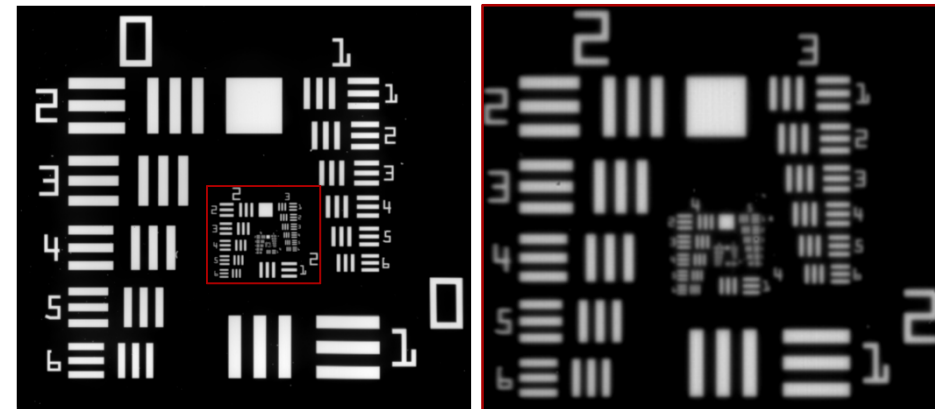


- Illuminate at angle: dark field measurement, filter unnecessary
- Optics + Camera on XYZ stage to image large samples

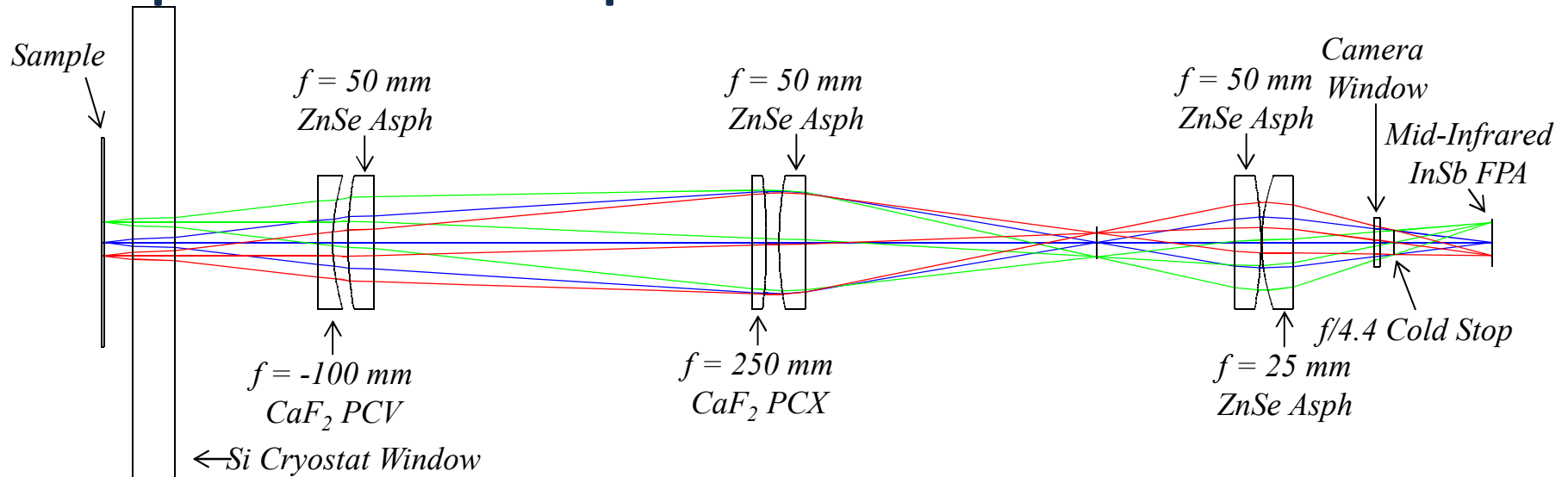
Experiment: Optics



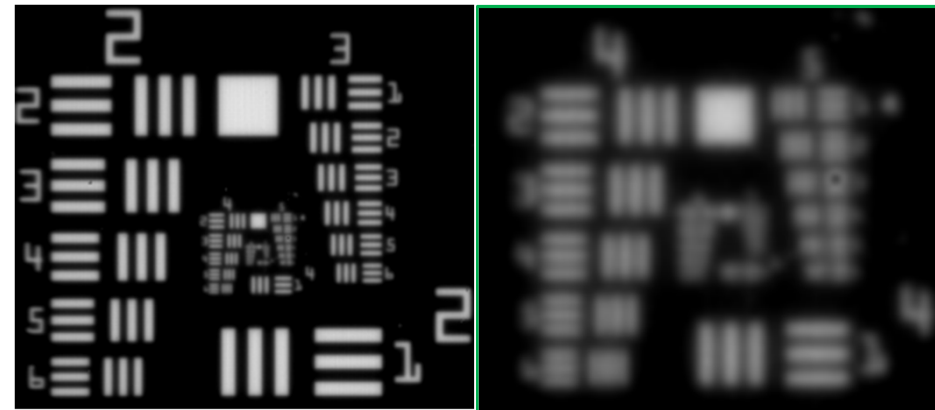
- Re-imaging design: high cold stop efficiency (low vignetting), object-side telecentric
- Stitching: distortion, vignetting very obvious
- Resolution: element (4,5) = 25 lp/mm = .04 mm/lp, close f/4 limit



Experiment: Optics

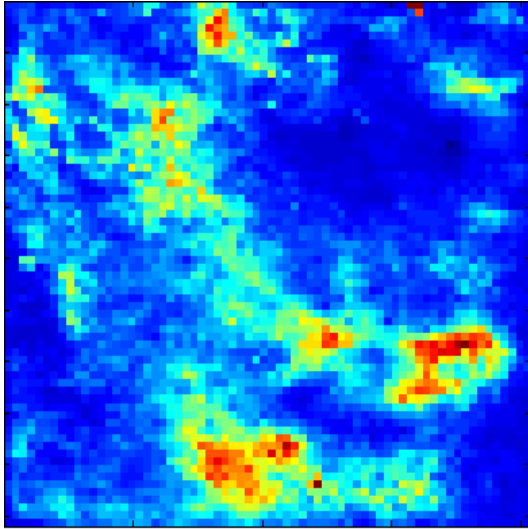


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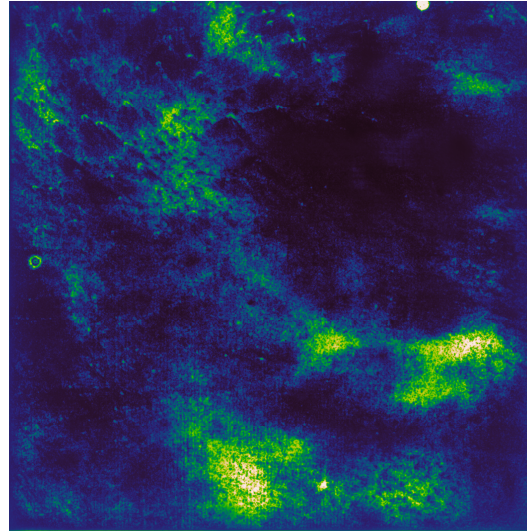


Results: PL, Dark Current, Response

Lifetime



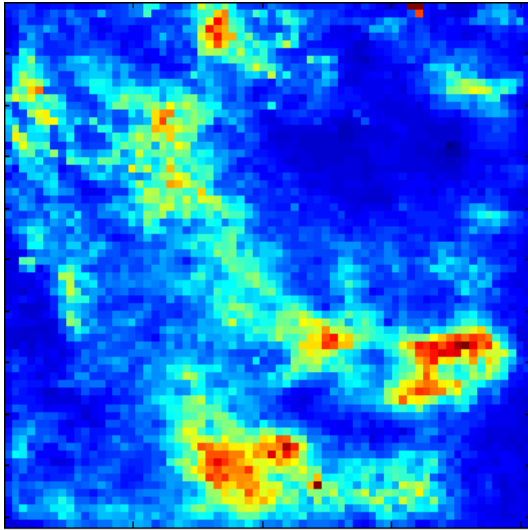
Intensity



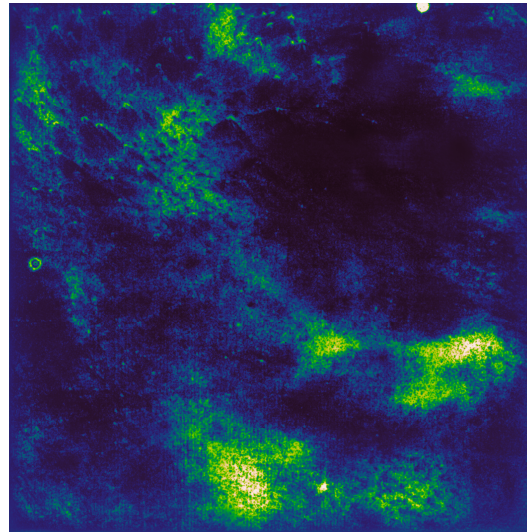
Bright areas = good:
long lifetime, high PL
intensity

Results: PL, Dark Current, Response

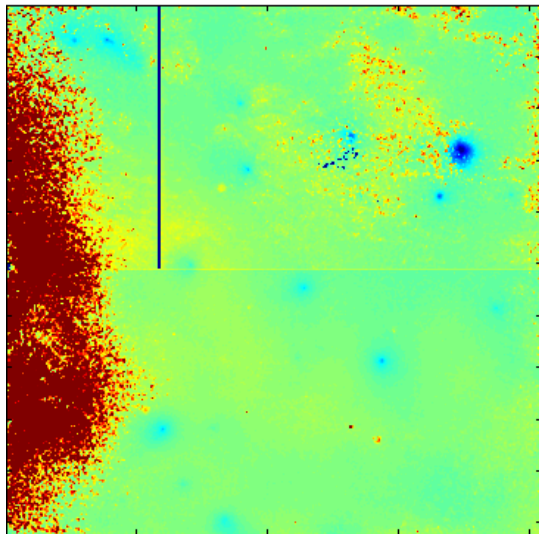
Lifetime



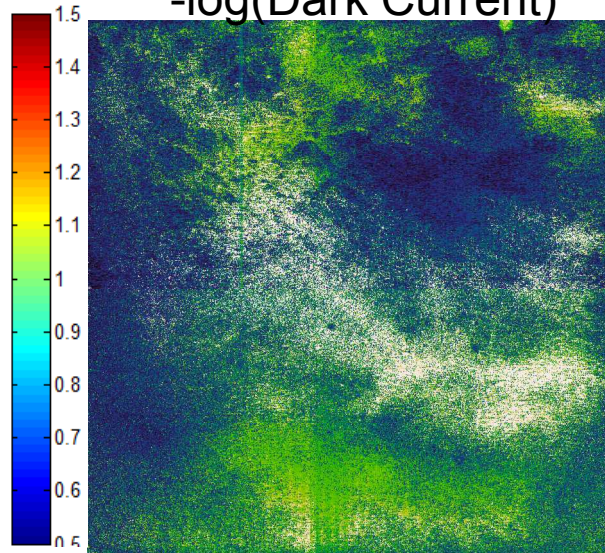
Intensity



Relative Response



$-\log(\text{Dark Current})$



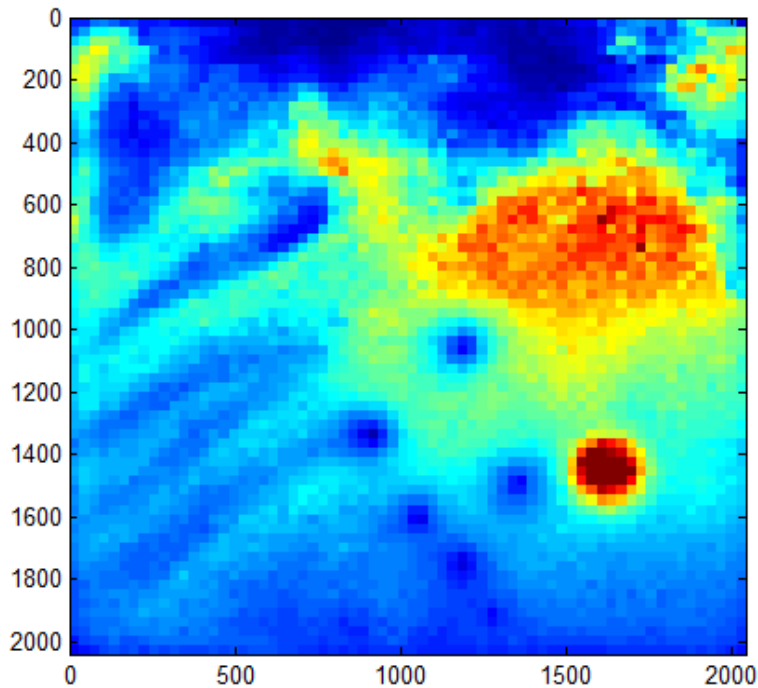
Bright areas = good:
long lifetime, high PL
intensity, low dark
current \therefore low defect
density

Dark current
measured at 100K, PL
at 110K

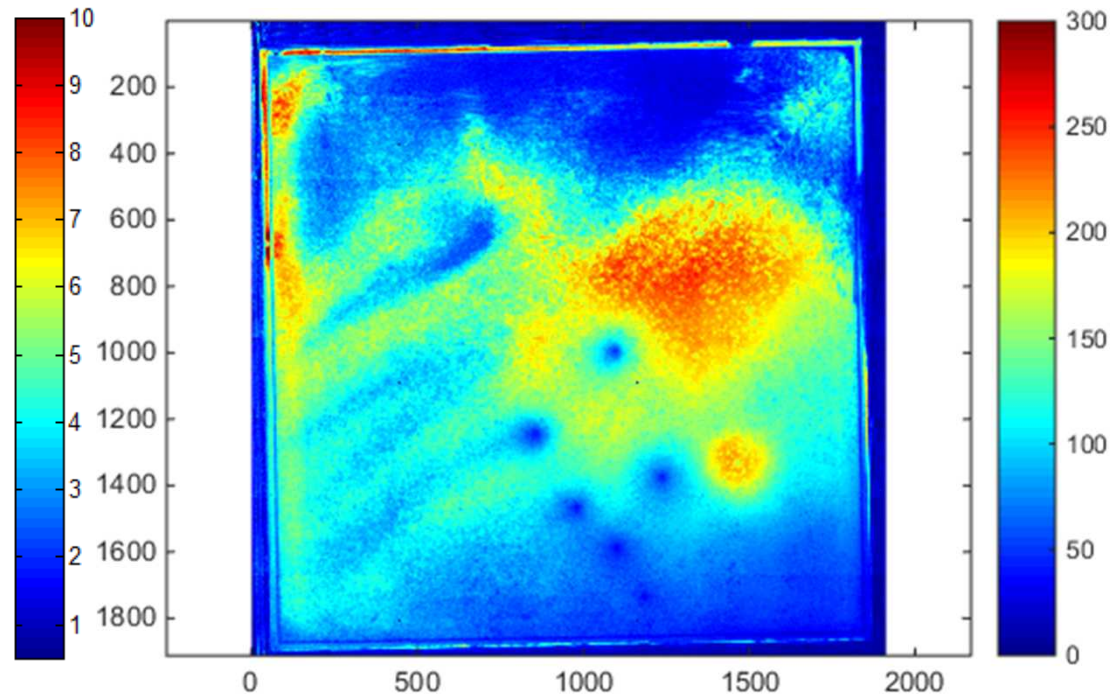
*Note inverted scale on
dark current!*

Results: FPA #2

Lifetime (μs), 0.5mm spot
Point-By-Point Mapping



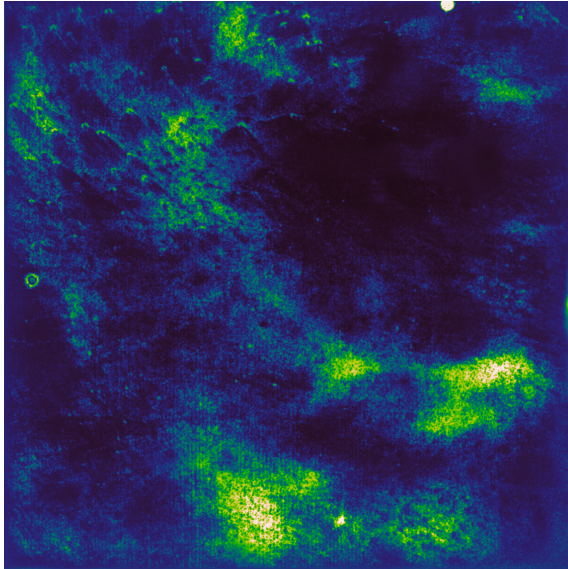
PL Intensity (a.u.)
CW Lamp Excitation, IR Camera



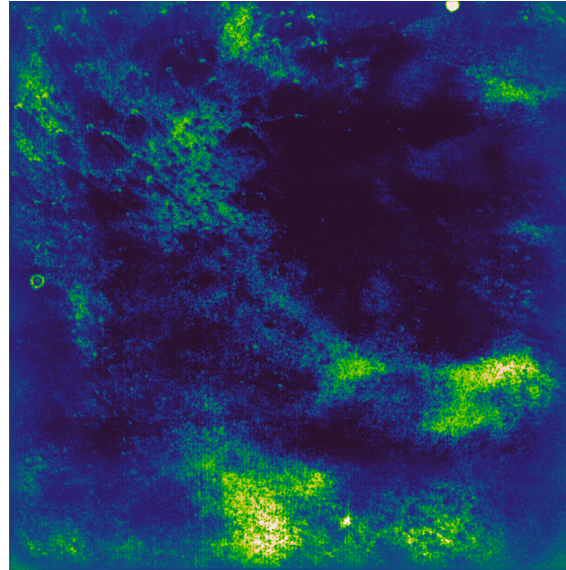
- Again see good correspondence between intensity and lifetime images

Temperature

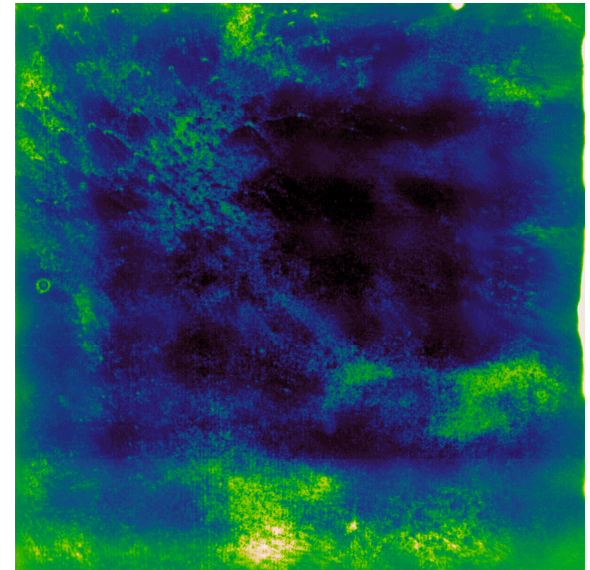
110 K



200 K



295 K

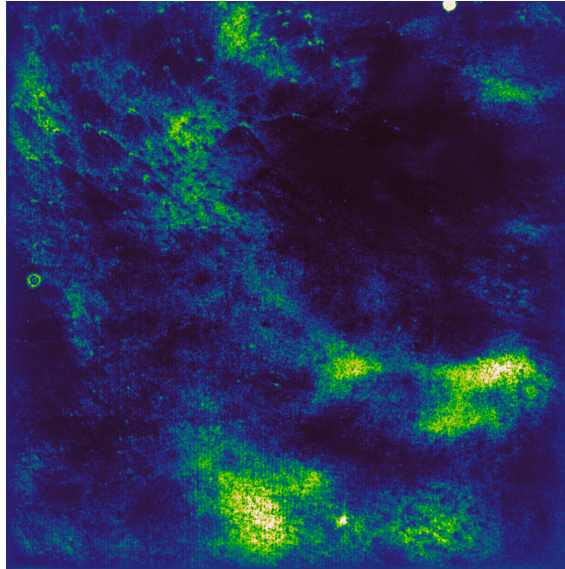


Most time consuming part of measurement is cooling!

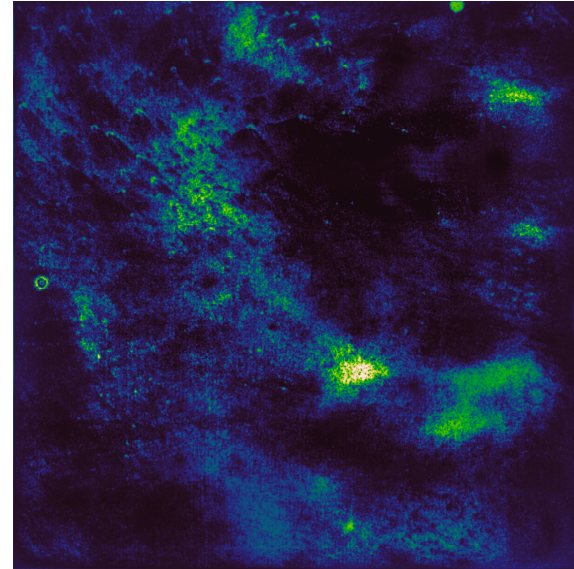
- 110 K: high vacuum pump-down + ~3 hours depending on safe cooling rate
- 200 K (-73 C): PL still very clear, potentially dry air or N₂ environment, easy to put optics in same environment which would reduce background
- 295 K: Increased background, still easy to identify good areas at RT!
 - PL Intensity ~ 4x lower than 110 K
 - Thermal self-emission from features near focus (e.g. top & bottom surface of detector, surrounding electronics), but not a problem if screening identical samples

Super-resolution

Mean of 10 Frames



Super-Resolution



- Collected 10 frames with 4.1 ms integration time for every image
- Camera closed-cycle cooler vibrates: ~ 1 px shift between frames when taking this set of images
- Left: averaged frames
- Right: Iterative coupled blind deconvolution and registration
- Only modest gains observed thus far

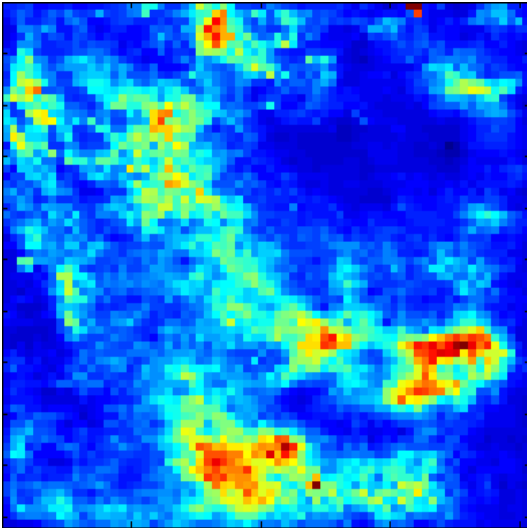
Conclusions

Demonstrated PL intensity can be used to rapidly screen semiconductor detectors for defects

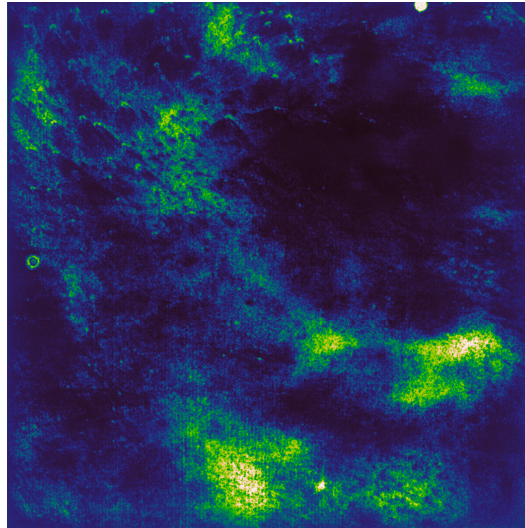
- Applicable at multiple stages in fabrication process from wafers to completed hybridized FPAs
- Measurement can be performed in moderate environments for rapid screening, or at the target operating temperature of the FPA
- Potentially allows for increasing fabrication yield: bin wafers after active layer growth, decide which sensors to hybridize, etc.
- Helps identify source of issues: differentiate between electrical issues and issues in active layer

Results: PL & Dark Current

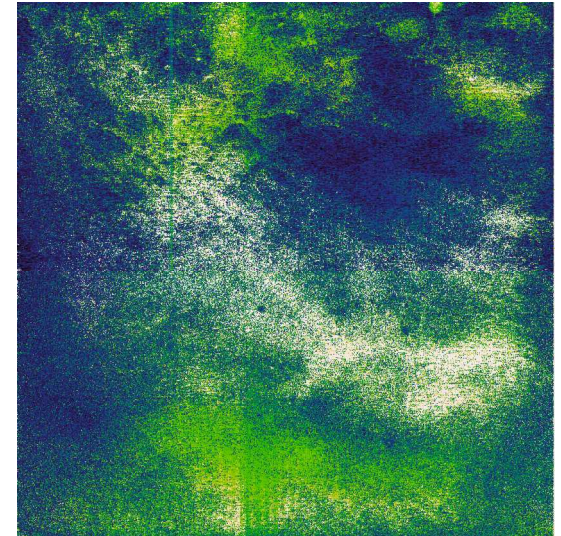
Lifetime



Intensity

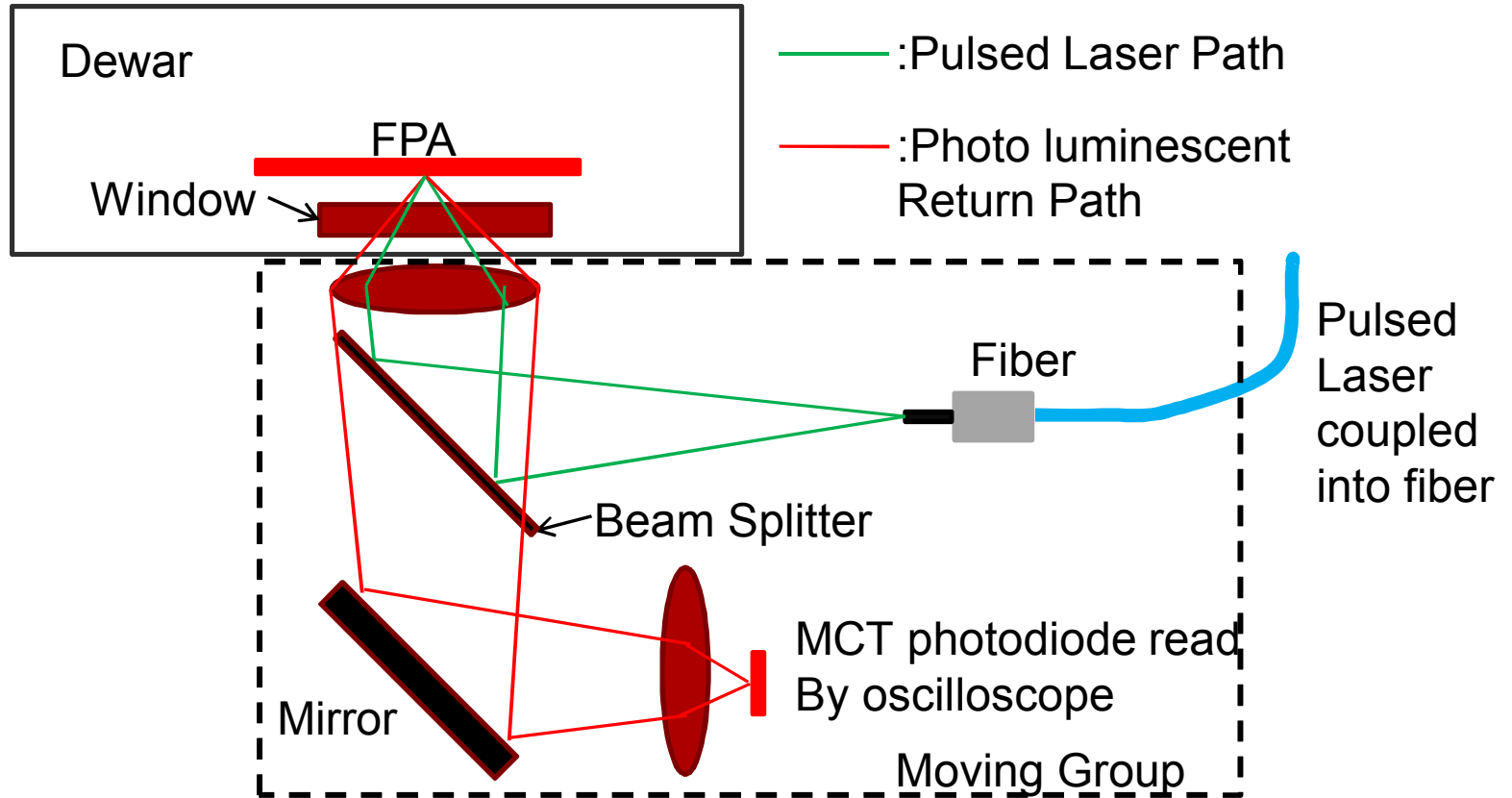


$-\log(\text{Dark Current})$
(bright = low!)

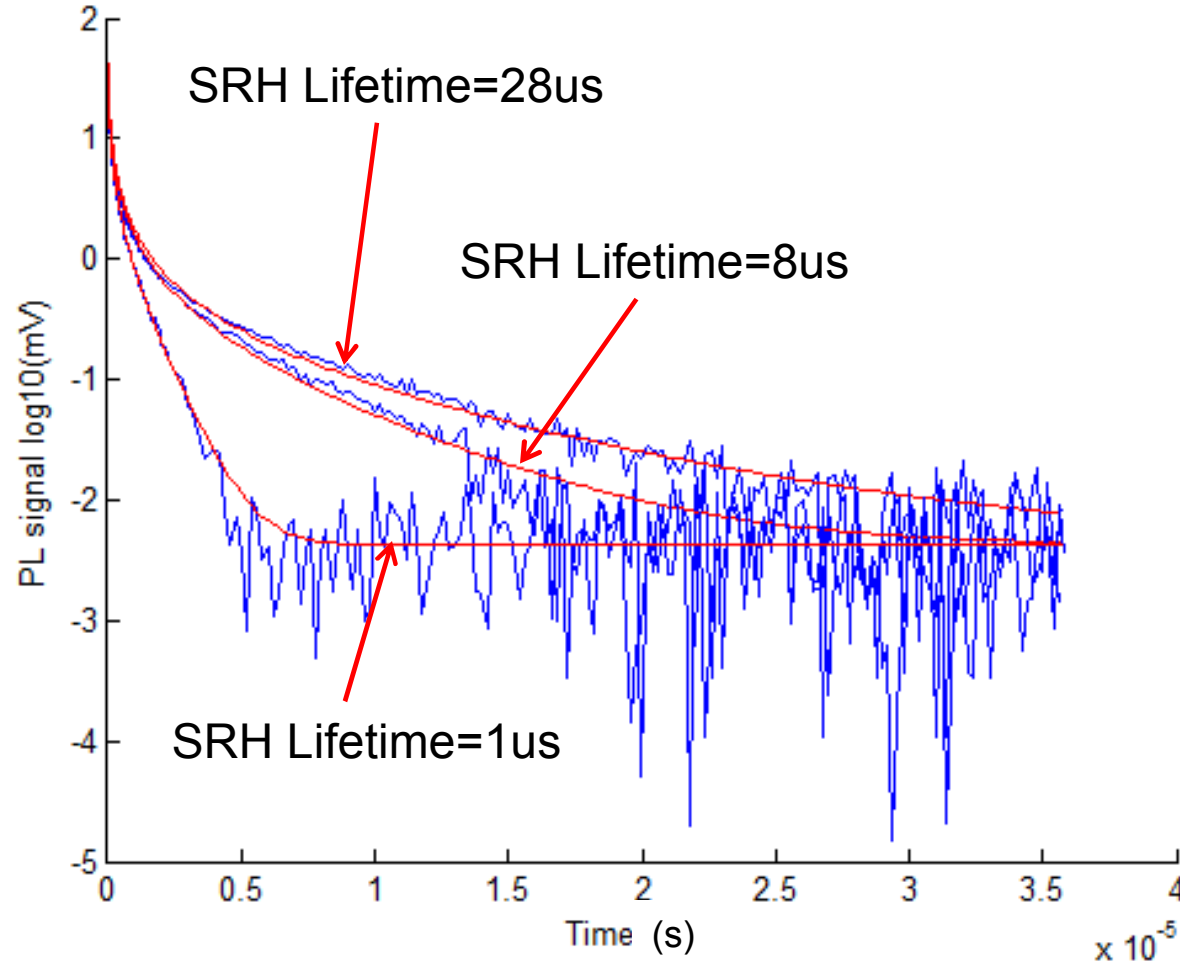


- Dark current measured at 100K, PL at 110K
- Bright areas = good: long lifetime, high PL intensity, low dark current
 \therefore low defect density
- *Note inverted scale on dark current!*

Time Resolved PL Experiment



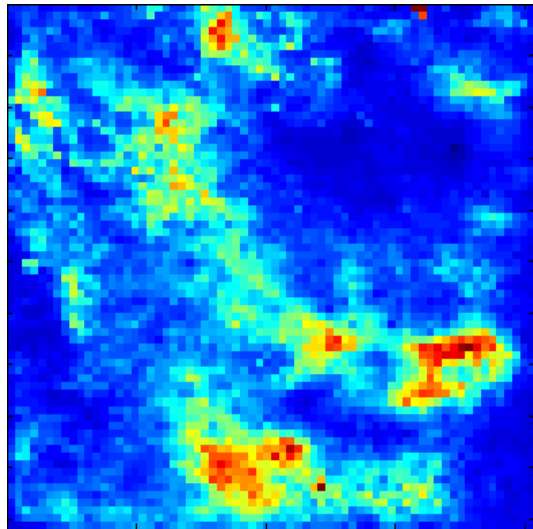
Time Resolved PL: Signal & Fit



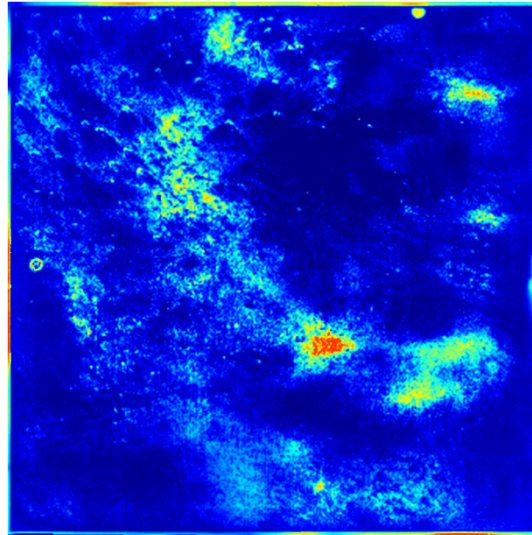
- The measurement is good enough to distinguish SRH lifetimes up to $\sim 50\mu\text{s}$ (beyond which the differences are below the noise floor)

BTB102 PL & Dark Current

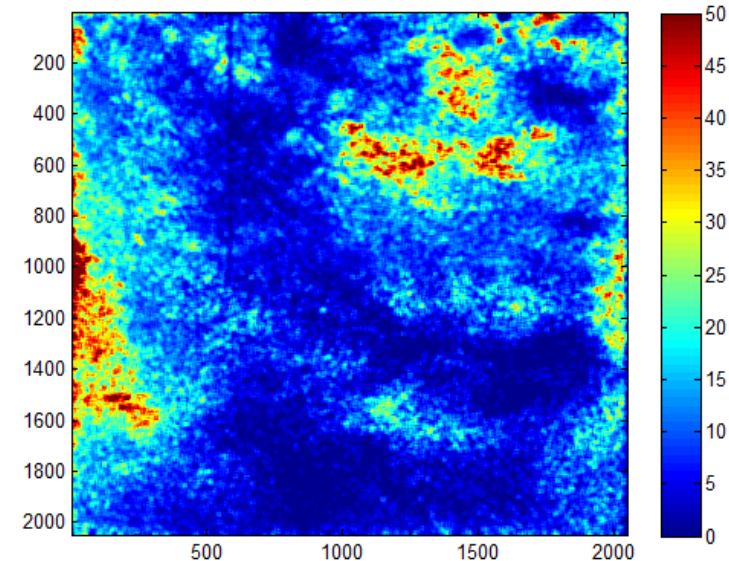
Lifetime



Intensity



Dark Current ($\mu\text{A}/\text{cm}^2$ @100K)



- Dark current measured at 100K, PL at 110K
- Dark areas in lifetime and intensity (high recombination rate) = poor areas of detector = bright areas in dark current